

### AMENDMENTS TO THE CLAIMS

Applicant submits below a complete listing of the current claims, including marked-up claims with insertions indicated by underlining and deletions indicated by strikeouts and/or double bracketing. This listing of claims replaces all prior versions, and listings, of claims in the application:

#### Listing of the Claims

1-28. (Canceled)

29. (Currently amended) An integrated circuit chip comprising:

a semiconductor substrate comprising at least one transistor; and

a pump in fluid communication with a ventilating duct and configured to provide  
pressure sufficient to set a fluid in motion through the ventilating duct so as to cool the integrated  
circuit chip, the pump comprising:

a cavity disposed on the semiconductor substrate;

a conductive layer covering at least a portion of an interior of the cavity;

a flexible membrane, including a conductive material, placed above the cavity;

a dielectric layer that provides insulation between portions of the conductive layer  
and the conductive material of the flexible membrane which are close to each other;

a pumping volume defined between the conductive layer and the flexible  
membrane;

at least one opening that provides fluid communication to the pumping volume  
through the conductive layer;

terminals to receive and apply voltage between the conductive layer and the  
flexible membrane to cause the flexible membrane to move; and

wherein the flexible membrane is configured to cover the at least one opening upon  
application of the voltage.

30. (Previously presented) The integrated circuit chip of claim 29, wherein the cavity  
has a cup shape so that an interval between the conductive layer and the membrane progressively

increases from a border, formed between the cavity and an upper surface of the substrate, to a bottom of the cavity.

31. (Previously presented) The integrated circuit chip of claim 29, wherein the at least one opening is positioned substantially at a bottom of the cavity.

32. (Previously presented) The integrated circuit chip of claim 29, further comprising a ventilating duct formed at least partially in the semiconductor substrate of the integrated circuit and that leads to the at least one opening.

33. (Previously presented) The integrated circuit chip of claim 29, wherein the dielectric layer is disposed on the conductive layer.

34. (Previously presented) The integrated circuit chip of claim 29, wherein the dielectric layer is disposed on the flexible membrane.

35. (Previously presented) The integrated circuit chip of claim 29, wherein the flexible membrane comprises a conductive material.

36. (Currently amended) The integrated circuit chip of claim 29, wherein the at least one opening comprises a first opening and a second opening, each opening providing fluid communication to the pumping volume through the conductive layer and configured to set the fluid in a directional motion.

37. (Previously presented) The integrated circuit chip of claim 36, further comprising a first ventilating duct formed at least partially in the semiconductor substrate of the integrated circuit and that leads to the first opening and a second ventilating duct formed at least partially in the semiconductor substrate and that leads to the second opening.

38. (Previously presented) The integrated circuit chip of claim 36, wherein application of the voltage to the terminals causes the flexible membrane to move toward the

conductive layer to close fluid communication between the second opening and the pumping volume.

39. (Currently amended) The integrated circuit chip of claim 36, wherein the second opening is positioned closer to a border of the cavity than the first opening is positioned to the border, the border being between the cavity and an upper surface of the substrate, and the first opening positioned closer to a center of the cavity than the second opening.

40. (Currently amended) The integrated circuit chip of claim 39, wherein upon application of a sufficient voltage between the conductive layer and the membrane, the flexible membrane is adapted to deform in a motion toward the conductive layer so as to cover the second opening and not the first opening.

41. (Previously presented) The integrated circuit chip of claim 36, wherein the flexible membrane is configured to cover at least the second opening when the voltage is applied.

42. (Previously presented) The integrated circuit chip of claim 36, wherein the second opening is larger than the first opening to promote the introduction of more air through the second opening than the first opening to the pumping volume when the voltage is reduced.

43. (Currently amended) An integrated circuit chip comprising:  
a semiconductor substrate comprising at least one transistor and at least one ventilating duct; and  
a pump configured to provide pressure sufficient to set a fluid in motion through the at least one ventilating duct so as to cool the integrated circuit chip, the pump being disposed on the semiconductor substrate and in fluid communication with the at least one ventilating duct.

44. (Previously presented) The integrated circuit chip of claim 43, wherein the pump comprises a cavity disposed on the semiconductor substrate.

45. (Previously presented) The integrated circuit chip of claim 44, wherein the pump comprises a conductive layer covering at least a portion of an interior of the cavity.

46. (Previously presented) The integrated circuit chip of claim 45, further comprising at least one opening that provides fluid communication between the at least one ventilating duct and the pump through the conductive layer.

47. (Previously presented) The integrated circuit chip of claim 44, wherein the pump comprises a flexible membrane that includes a conductive material, wherein the flexible membrane is disposed above the cavity.

48. (Previously presented) The integrated circuit chip of claim 47, wherein the pump comprises a dielectric layer that provides insulation between portions of a conductive layer and the conductive material of the flexible membrane, the conductive layer and the conductive material being in close proximity to one another.

49. (Currently amended) The integrated circuit chip of claim 48, wherein the pump comprises terminals to receive and apply voltage between the conductive layer and the flexible membrane to cause the flexible membrane to move.

50. (Previously presented) The integrated circuit chip of claim 49, wherein the flexible membrane is configured to cover at least one opening in the conductive layer that provides fluid communication between the pump and the at least one ventilating duct upon application of the voltage.